

2、 Specification

2.1 Main Specifications

Specification	
SOC	Rockchip RK3399 (28nm HKMG Process)
CPU	Six-Core ARM 64-bit processor, up to 1.8GHz Based on Big.Little architecture, Dual-Core Cortex-A72 and Quad-Core Cortex-A53 with separate NEON coprocessor
GPU	ARM® Mali-T860 MP4 Quad-core GPU Support OpenGL ES1.1/2.0/3.0/3.1, OpenVG1.1, OpenCL, DX11 Support AFBC(frame buffer compression)
NPU	Onboard AI neural network processor SPR2801S: Computing power up to 2.8 TOPS , peak up to 5.6Tops , 9.3Tops/W ultra-high efficiency Support PLAI (PyTorch) and MDK (Caffe) model training tools Follow-up support TensorFlow Support Image Classification Model VGG-16(GNet1)、 GNet18 and Gnetfc Support Target Detection Model: SSD (Based on VGG)
RAM	2GB/4GB LPDDR4
Storage	16GB High-Speed eMMC, Support TF Card Slot
Network	Gigabit Ethernet (RJ45 interface) WIFI/BT module, support 2.4GHz / 5GHz dual-band WiFi, 802.11a/b/g/n/ac protocol Support Bluetooth 4.1 Mini PCIe (Used to expand 3G/4G modules, use with Micro SIM card slot)
Multimedia	Support 4K VP9 and 4K 10bits H265/H264 video decoding, up to 60fps 1080P Multi-format video decoding (VC-1 , MPEG-1/2/4 , VP8) 1080P video encoding , Support H.264 , VP8 formats Video post processor: deinterlacing, denoising, edge/ detail/ color optimization
Display	HDMI2.0 support 4K 60Hz display, support HDCP 1.4/2.2 Support DisplayPort 1.2 (4 lines, up to 4K 60Hz) Dual VOP: Support 4096X2160 and 2560X1600 Support dual-screen identical display/dual-screen differential display Scalable: eDP 1.3(4 lines10.8Gbps), Dual LVDS (6/8 bit, up to 24-bit 1920×1200 resolution) Support single channel MIPI DSI, up to 1920x1080 resolution (customized interface)
Other	Support USB3.0 HOST and Type-C interface ADC×1, SPI / GPIO, Controllable LED×2, I ² C×1, Gravity sensor×1(Scalable)
Audio	1xPHONE, 2xSPEAKER(L/R), 1xLINE-IN, 1xLINE-OUT
USB	Type-C (OTG), 1 x USB3.0, 4 x USB2.0(Interface x 2, socket x 2)
Key	Power (Key x 1, socket x 1), Recover(Key x 1, socket x 1)
Serial port	RS232×1, RS485×1, Debug serial port×1, Onboard 2-way TTL
IR	With a one-way infrared receiver, Support infrared remote control
OS	Support Android, Linux, Ubuntu System
Power	DC 12V-2A (DC5.5 × 2.1mm)

2.2 Power Parameter

Type	Min	Typical	Max
Operating Voltage	6 v	12 v	24v
Operating Current	500mA	1 A	2A

2.3 Environmental Parameter

Type	Min	Typical	Max
Operating Temperature	-20 °C	25 °C	60 °C
Storage Temperature	-40 °C	25 °C	125 °C

2.4 Appearance Structure

Type	Min
Size	160 x 94 x 26 mm
Appearance	AL6063 aluminum profile

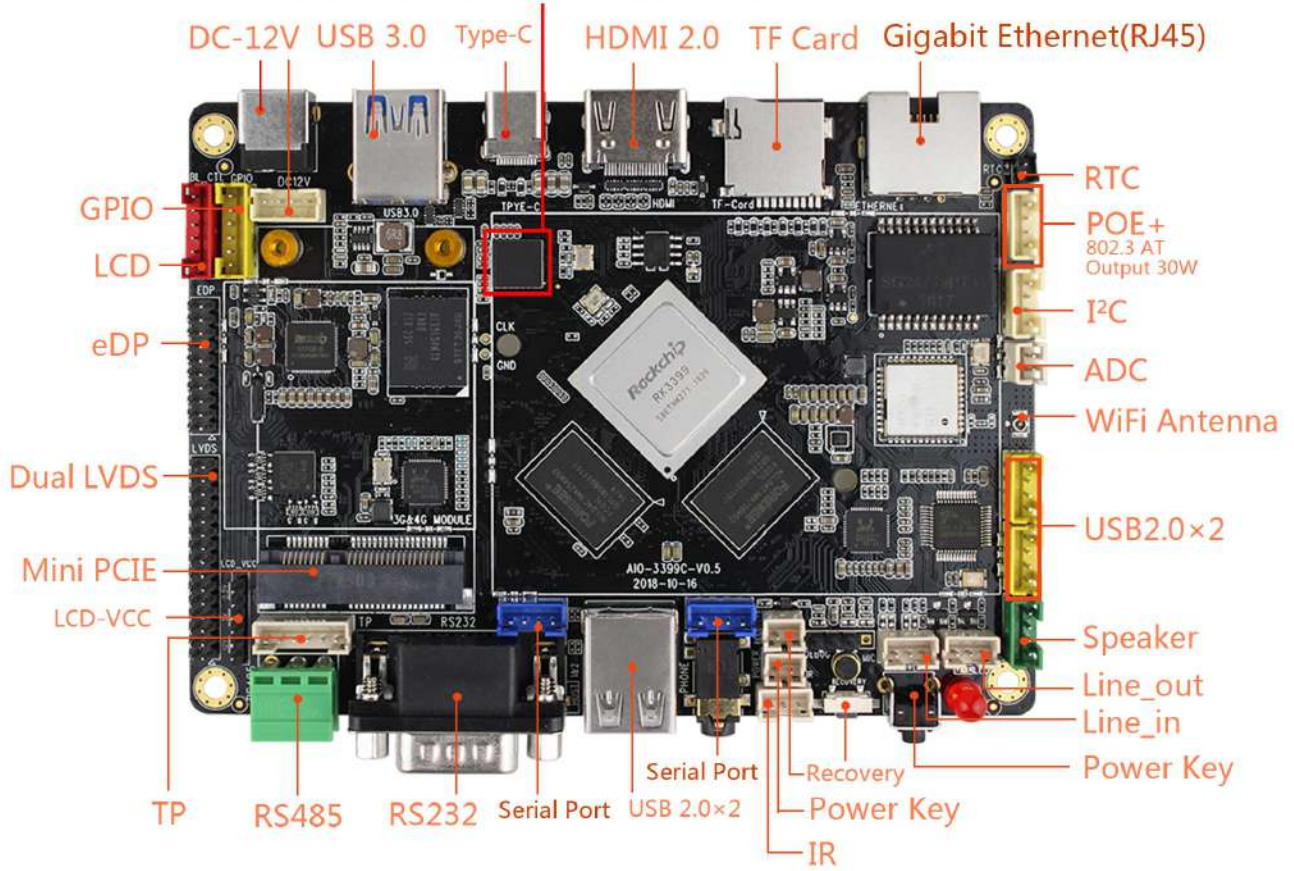
3. Interface

High-quality metal case and fanless design configured, heat-conducting aluminum alloy structure, high-efficiency cooling, 60°C high-temperature aging, stable operation for 7x24 hours, various installation ways contributing to its embedding into various smart devices more convenient.

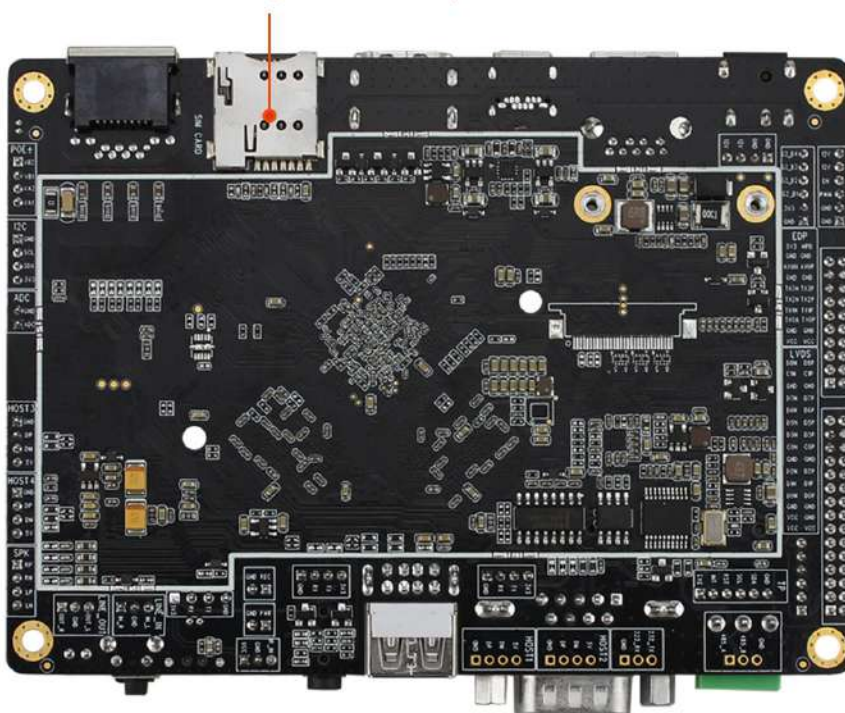


4.Interface description

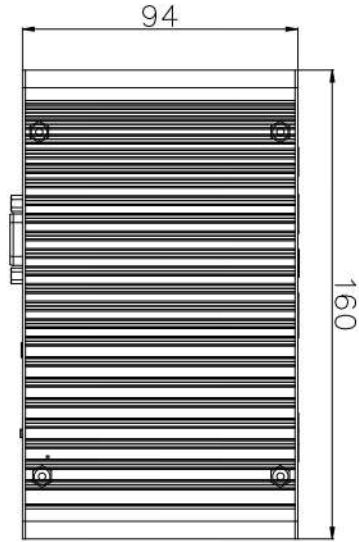
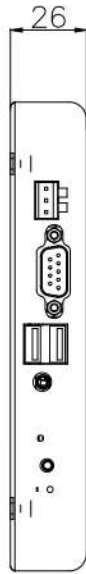
Artificial Intelligence Processor NPU



SIM Card (MicroSIM)



5. Size



比例
1.000

